

## Features

- High blocking voltage with low on-resistance
- High-speed switching with low capacitances
- Fast intrinsic diode with low reverse recovery ( $Q_{rr}$ )
- Halogen free, RoHS compliant

## Benefits

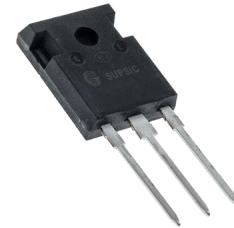
- Reduce switching losses and minimize gate ringing
- Higher system efficiency
- Reduce cooling requirements
- Increase power density
- Increase system switching frequency

## Applications

- Solar inverters
- EV motor drive
- High voltage DC/DC converters
- Switched mode power supplies

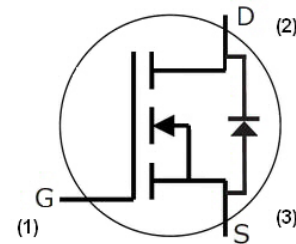
| Part Number  | Package  |
|--------------|----------|
| GC3M0040120D | TO-247-3 |

|                          |               |
|--------------------------|---------------|
| $V_{DS}$                 | 1200 V        |
| $I_D @ 25^\circ\text{C}$ | 66 A          |
| $R_{DS(on)}$             | 40 m $\Omega$ |



TO-247-3

## Package



## Maximum Ratings ( $T_c = 25^\circ\text{C}$ unless otherwise specified)

| Symbol         | Parameter                                  | Value       | Unit             | Test Conditions                                   | Note    |
|----------------|--|-------------|------------------|---|---------|
| $V_{DSmax}$    | Drain - Source Voltage                     | 1200        | V                | $V_{GS} = 0\text{ V}, I_D = 100\ \mu\text{A}$     |         |
| $V_{GSmax}$    | Gate - Source Voltage (dynamic)            | -8/+19      | V                | AC ( $f > 1\text{ Hz}$ )                          | Note 1  |
| $V_{GSop}$     | Gate - Source Voltage (static)             | -4/+15      | V                | Static  | Note 2  |
| $I_D$          | Continuous Drain Current                   | 66          | A                | $V_{GS} = 15\text{ V}, T_c = 25^\circ\text{C}$    | Fig. 19 |
|                |  | 48          |                  | $V_{GS} = 15\text{ V}, T_c = 100^\circ\text{C}$   |         |
| $I_{D(pulse)}$ | Pulsed Drain Current                       | 100         | A                | Pulse width $t_p$ limited by $T_{jmax}$           |         |
| $P_D$          | Power Dissipation                          | 326         | W                | $T_c = 25^\circ\text{C}, T_j = 175^\circ\text{C}$ | Fig. 20 |
| $T_J, T_{stg}$ | Operating Junction and Storage Temperature | -40 to +175 | $^\circ\text{C}$ |   |         |
| $T_L$          | Solder Temperature                         | 260         | $^\circ\text{C}$ | 1.6mm (0.063") from case for 10s                  |         |
| $M_d$          | Mounting Torque                            | 1           | Nm               | M3 or 6-32 screw                                  |         |
|                |  | 8.8         |                  |   |         |

Note (1): When using MOSFET Body Diode  $V_{GSmax} = -4\text{V}/+19\text{V}$

Note (2): MOSFET can also safely operate at 0/+15 V

**Electrical Characteristics** ( $T_c = 25^\circ\text{C}$  unless otherwise specified)

| Symbol        | Parameter                                  | Min. | Typ. | Max. | Unit          | Test Conditions   | Note         |
|---------------|--|------|------|------|---------------|---|--------------|
| $V_{(BR)DSS}$ | Drain-Source Breakdown Voltage             | 1200 |      |      | V             | $V_{GS} = 0\text{ V}, I_D = 100\ \mu\text{A}$   |              |
| $V_{GS(th)}$  | Gate Threshold Voltage                     | 1.8  | 2.7  | 3.6  | V             | $V_{DS} = V_{GS}, I_D = 9.5\ \text{mA}$   | Fig. 11      |
|               |  |      | 2.2  |      | V             | $V_{DS} = V_{GS}, I_D = 9.5\ \text{mA}, T_J = 175^\circ\text{C}$  |              |
| $I_{DSS}$     | Zero Gate Voltage Drain Current            |      | 1    | 50   | $\mu\text{A}$ | $V_{DS} = 1200\ \text{V}, V_{GS} = 0\ \text{V}$   |              |
| $I_{GSS}$     | Gate-Source Leakage Current                |      | 10   | 250  | nA            | $V_{GS} = 15\ \text{V}, V_{DS} = 0\ \text{V}$   |              |
| $R_{DS(on)}$  | Drain-Source On-State Resistance           |      | 40   | 53.5 | m $\Omega$    | $V_{GS} = 15\ \text{V}, I_D = 33.3\ \text{A}$   | Fig. 4, 5, 6 |
|               |  |      | 68   |      |               | $V_{GS} = 15\ \text{V}, I_D = 33.3\ \text{A}, T_J = 175^\circ\text{C}$  |              |
| $g_{fs}$      | Transconductance                           |      | 21   |      | S             | $V_{DS} = 20\ \text{V}, I_{DS} = 33.3\ \text{A}$  | Fig. 7       |
|               |  |      | 20   |      |               | $V_{DS} = 20\ \text{V}, I_{DS} = 33.3\ \text{A}, T_J = 175^\circ\text{C}$   |              |
| $C_{iss}$     | Input Capacitance                          |      | 2900 |      | pF            | $V_{GS} = 0\ \text{V}, V_{DS} = 1000\ \text{V}$<br>$f = 100\ \text{kHz}$<br>$V_{AC} = 25\ \text{mV}$  | Fig. 17, 18  |
| $C_{oss}$     | Output Capacitance                         |      | 103  |      |               |   |              |
| $C_{riss}$    | Reverse Transfer Capacitance               |      | 5    |      |               |   |              |
| $E_{oss}$     | $C_{oss}$ Stored Energy                    |      | 60   |      | $\mu\text{J}$ |   | Fig. 16      |
| $E_{ON}$      | Turn-On Switching Energy (SiC Diode FWD)   |      | 950  |      | $\mu\text{J}$ | $V_{DS} = 800\ \text{V}, V_{GS} = -4\ \text{V}/+15\ \text{V},$<br>$I_D = 33.3\ \text{A},$<br>$R_{G(ext)} = 2.5\ \Omega, L = 99\ \mu\text{H}, T_J = 175^\circ\text{C}$                     | Fig. 26      |
| $E_{OFF}$     | Turn Off Switching Energy (SiC Diode FWD)  |      | 346  |      |               |   |              |
| $E_{ON}$      | Turn-On Switching Energy (Body Diode FWD)  |      | 1645 |      | $\mu\text{J}$ | $V_{DS} = 800\ \text{V}, V_{GS} = -4\ \text{V}/+15\ \text{V},$<br>$I_D = 33.3\ \text{A},$<br>$R_{G(ext)} = 2.5\ \Omega, L = 99\ \mu\text{H}, T_J = 175^\circ\text{C}$                     | Fig. 26      |
| $E_{OFF}$     | Turn Off Switching Energy (Body Diode FWD) |      | 287  |      |               |   |              |
| $t_{d(on)}$   | Turn-On Delay Time                         |      | 15   |      | ns            | $V_{DD} = 800\ \text{V}, V_{GS} = -4\ \text{V}/15\ \text{V}$<br>$R_{G(ext)} = 2.5\ \Omega, I_D = 33.3\ \text{A}$<br>Timing relative to $V_{DS}$ , Inductive load<br>$L = 99\ \mu\text{H}$ | Fig. 27      |
| $t_r$         | Rise Time                                  |      | 60   |      |               |   |              |
| $t_{d(off)}$  | Turn-Off Delay Time                        |      | 25   |      |               |   |              |
| $t_f$         | Fall Time                                  |      | 12   |      |               |   |              |
| $R_{G(int)}$  | Internal Gate Resistance                   |      | 3.5  |      | $\Omega$      | $f = 1\ \text{MHz}, V_{AC} = 25\ \text{mV}$   |              |
| $Q_{gs}$      | Gate to Source Charge                      |      | 32   |      | nC            | $V_{DS} = 800\ \text{V}, V_{GS} = -4\ \text{V}/15\ \text{V}$<br>$I_D = 33.3\ \text{A}$<br>Per IEC60747-8-4 pg 21  | Fig. 12      |
| $Q_{gd}$      | Gate to Drain Charge                       |      | 29   |      |               |   |              |
| $Q_g$         | Total Gate Charge                          |      | 101  |      |               |   |              |

**Reverse Diode Characteristics** ( $T_c = 25^\circ\text{C}$  unless otherwise specified)

| Symbol         | Parameter                        | Typ. | Max. | Unit | Test Conditions   | Note          |
|----------------|----------------------------------|------|------|------|---|---------------|
| $V_{SD}$       | Diode Forward Voltage            | 5.5  |      | V    | $V_{GS} = -4\text{ V}, I_{SD} = 20\text{ A}, T_J = 25^\circ\text{C}$  | Fig. 8, 9, 10 |
|                |                                  | 4.9  |      | V    | $V_{GS} = -4\text{ V}, I_{SD} = 20\text{ A}, T_J = 175^\circ\text{C}$   |               |
| $I_S$          | Continuous Diode Forward Current |      | 51   | A    | $V_{GS} = -4\text{ V}, T_c = 25^\circ\text{C}$  | Note 1        |
| $I_{S, pulse}$ | Diode pulse Current              |      | 100  | A    | $V_{GS} = -4\text{ V}$ , pulse width $t_p$ limited by $T_{jmax}$  | Note 1        |
| $t_{rr}$       | Reverse Recover time             | 45   |      | ns   | $V_{GS} = -4\text{ V}, I_{SD} = 33.3\text{ A}, V_R = 800\text{ V}$<br>$dif/dt = 1150\text{ A}/\mu\text{s}, T_J = 175^\circ\text{C}$ | Note 1        |
| $Q_{rr}$       | Reverse Recovery Charge          | 697  |      | nC   |   |               |
| $I_{rrm}$      | Peak Reverse Recovery Current    | 26   |      | A    |   |               |
| $t_{rr}$       | Reverse Recover time             | 53   |      | ns   | $V_{GS} = -4\text{ V}, I_{SD} = 33.3\text{ A}, V_R = 800\text{ V}$<br>$dif/dt = 800\text{ A}/\mu\text{s}, T_J = 175^\circ\text{C}$  |               |
| $Q_{rr}$       | Reverse Recovery Charge          | 624  |      | nC   |   |               |
| $I_{rrm}$      | Peak Reverse Recovery Current    | 17   |      | A    |   |               |

**Thermal Characteristics**

| Symbol          | Parameter                                   | Typ. | Unit                      | Test Conditions | Note    |
|-----------------|---|------|---------------------------|-----------------|---------|
| $R_{\theta JC}$ | Thermal Resistance from Junction to Case    | 0.46 | $^\circ\text{C}/\text{W}$ |                 | Fig. 21 |
| $R_{\theta JA}$ | Thermal Resistance From Junction to Ambient | 40   |                           |                 |         |

Typical Performance

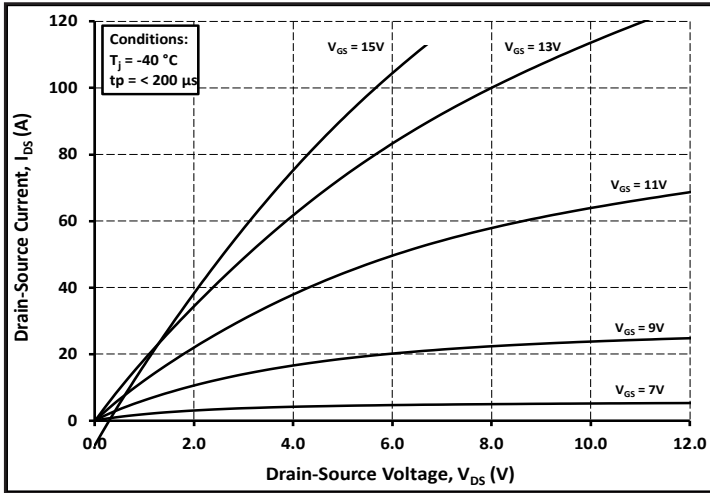


Figure 1. Output Characteristics  $T_J = -40\text{ }^\circ\text{C}$

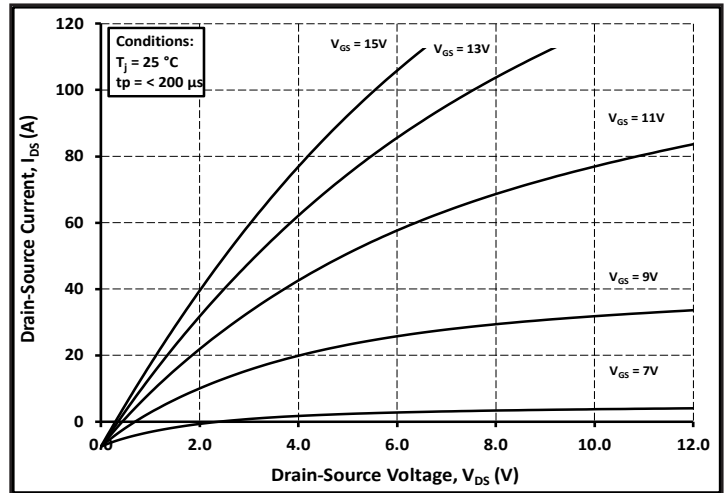


Figure 2. Output Characteristics  $T_J = 25\text{ }^\circ\text{C}$

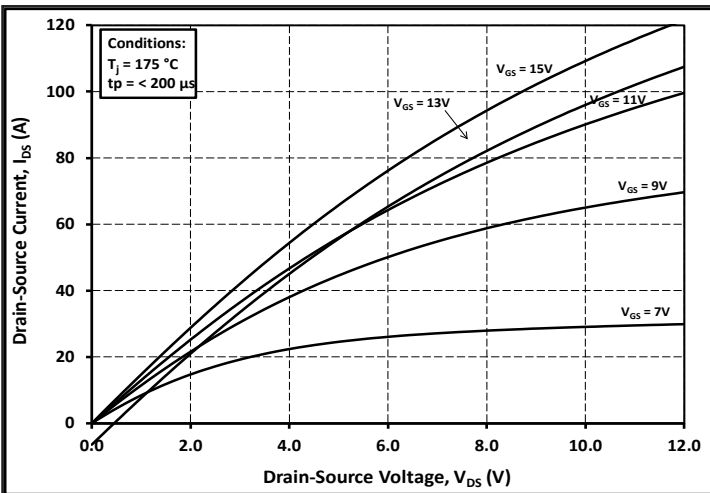


Figure 3. Output Characteristics  $T_J = 175\text{ }^\circ\text{C}$

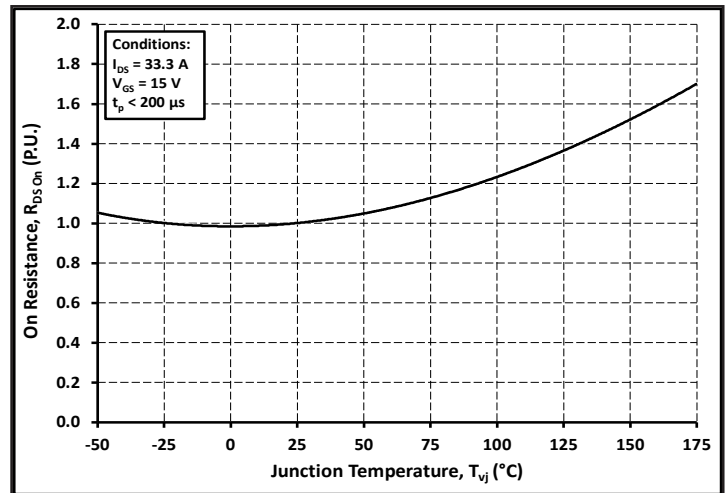


Figure 4. Normalized On-Resistance vs. Temperature

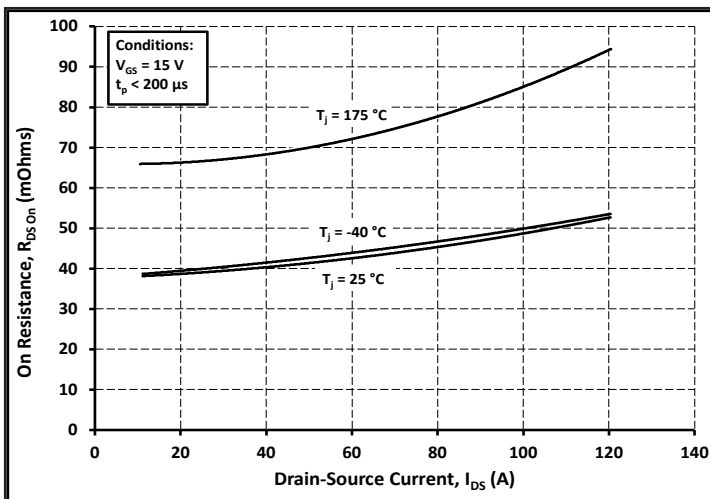


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

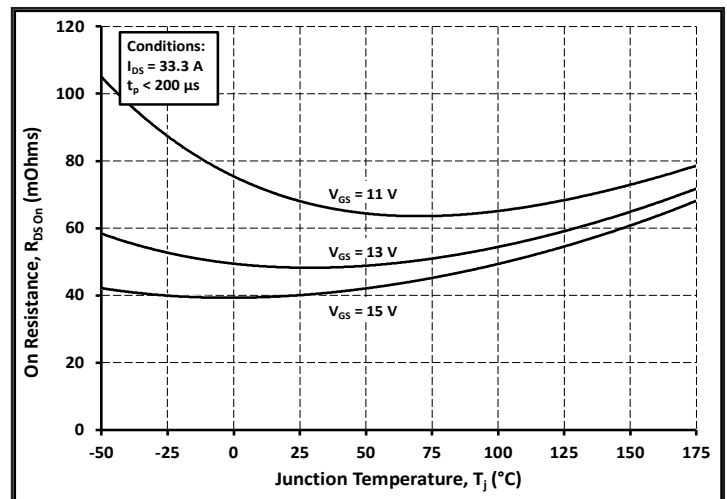


Figure 6. On-Resistance vs. Temperature For Various Gate Voltage

Typical Performance

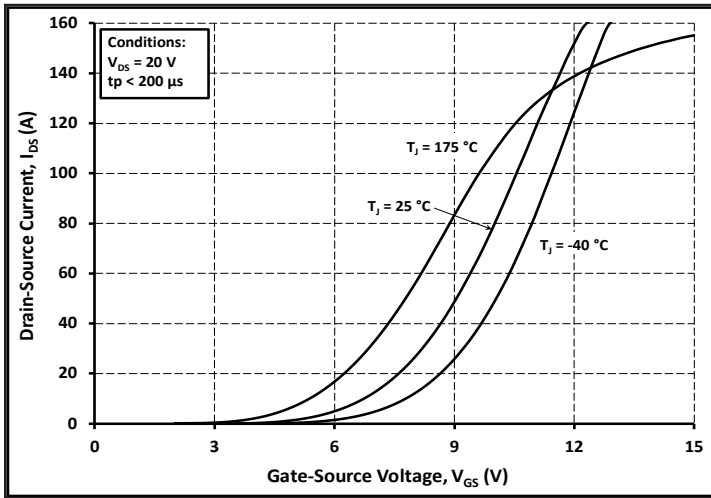


Figure 7. Transfer Characteristic for Various Junction Temperatures

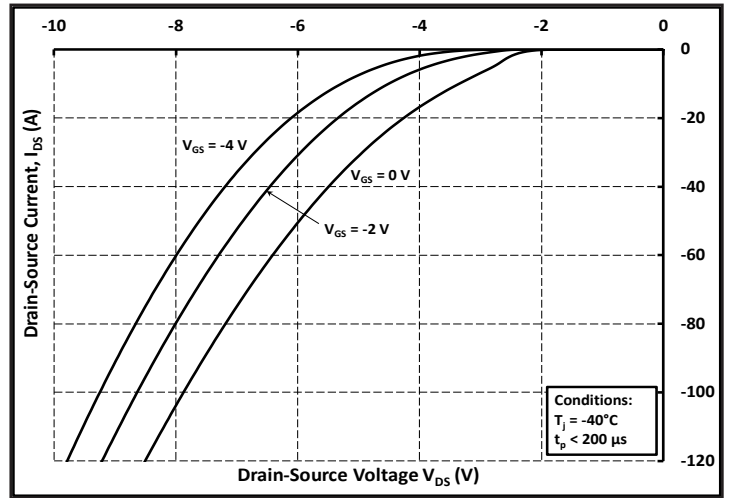


Figure 8. Body Diode Characteristic at -40 °C

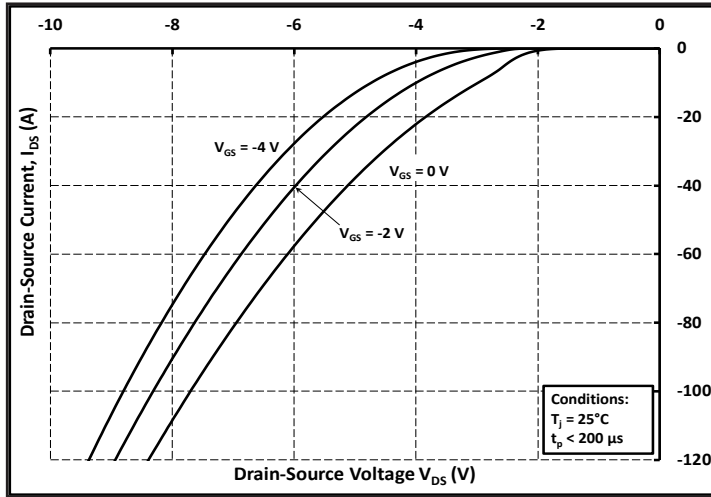


Figure 9. Body Diode Characteristic at 25 °C

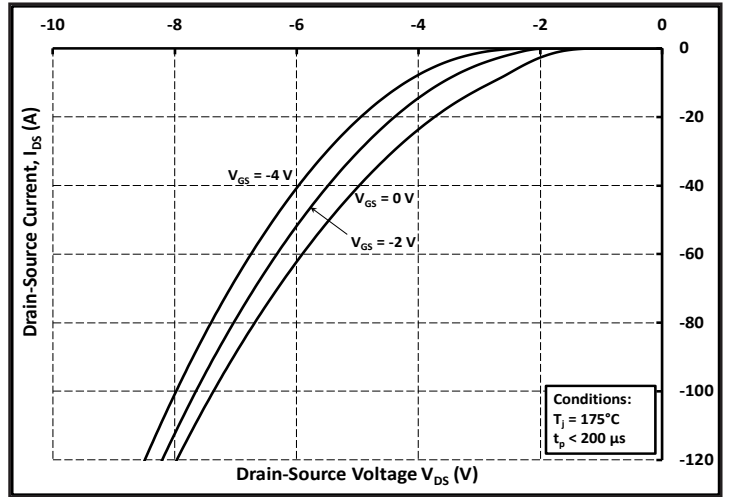


Figure 10. Body Diode Characteristic at 175 °C

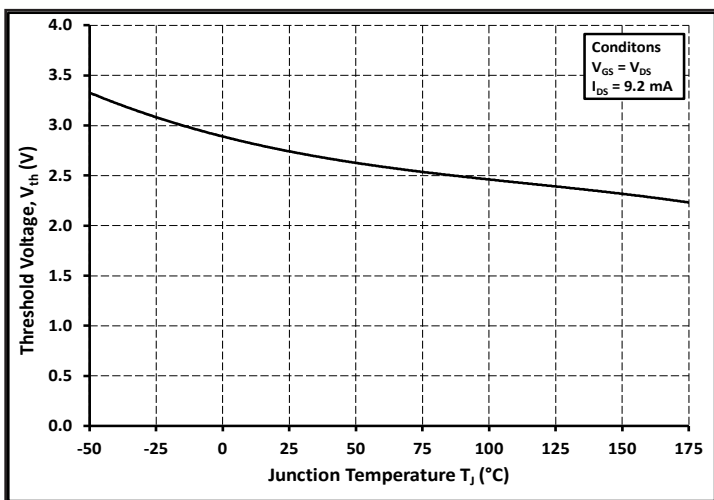


Figure 11. Threshold Voltage vs. Temperature

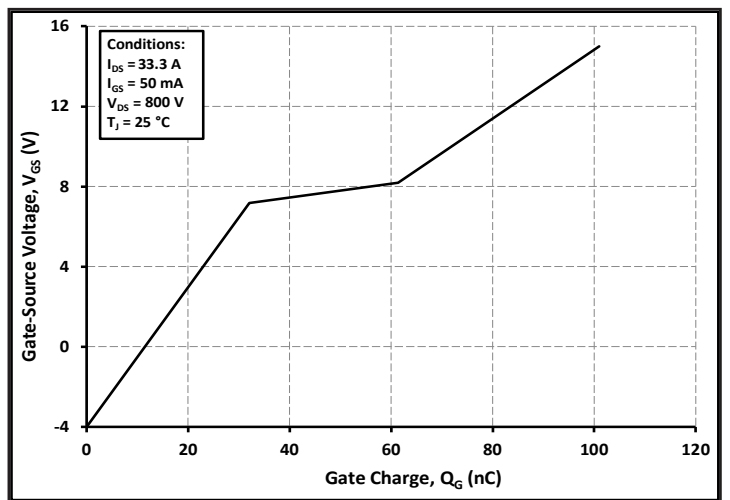


Figure 12. Gate Charge Characteristics

Typical Performance

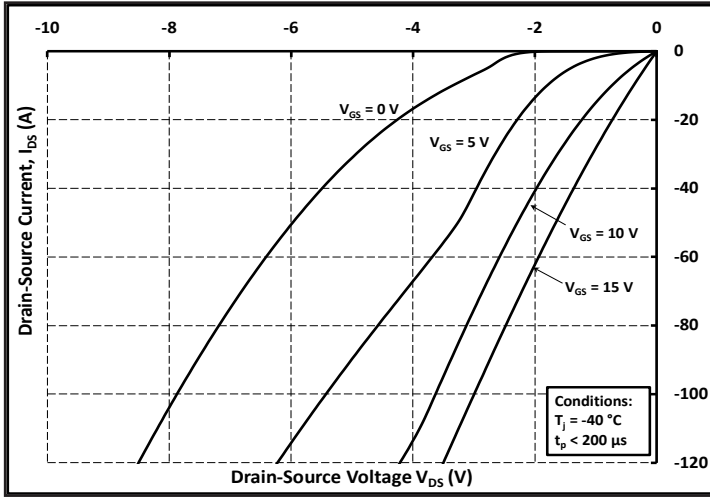


Figure 13. 3rd Quadrant Characteristic at -40 °C

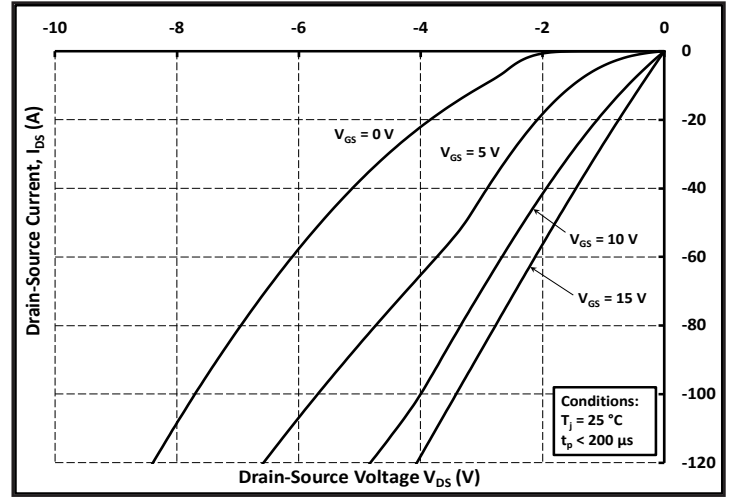


Figure 14. 3rd Quadrant Characteristic at 25 °C

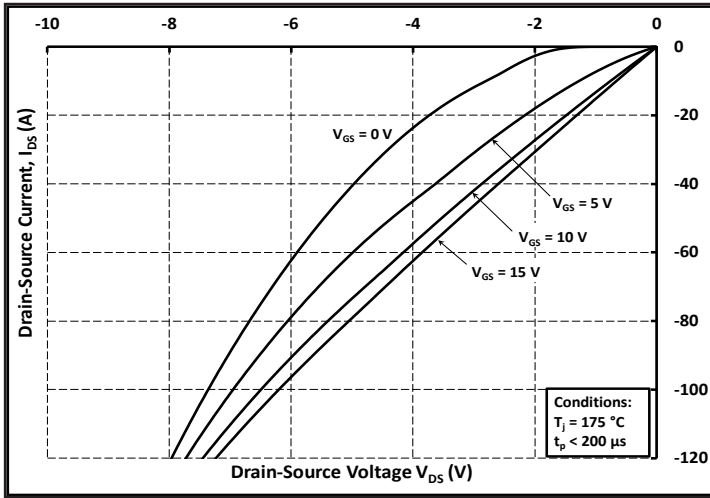


Figure 15. 3rd Quadrant Characteristic at 175 °C

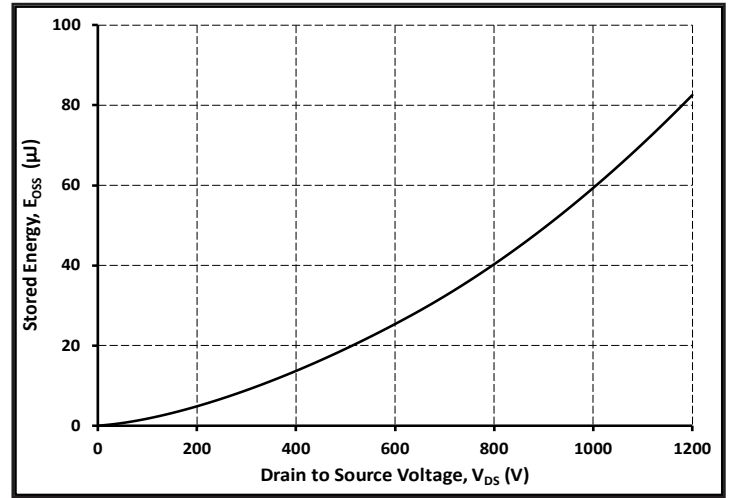


Figure 16. Output Capacitor Stored Energy

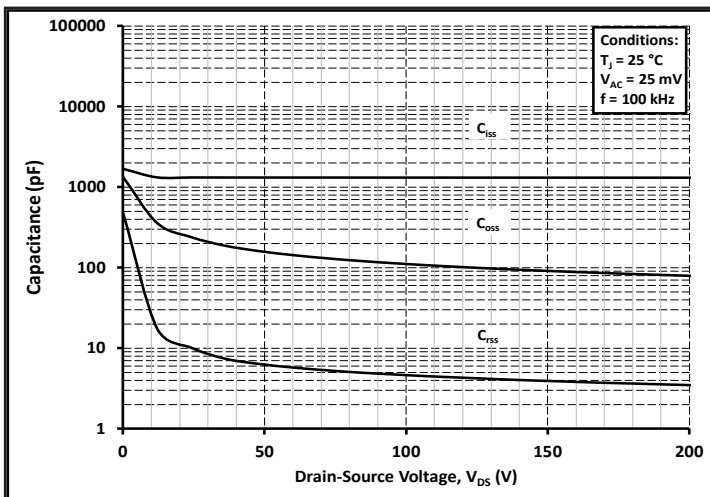


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200V)

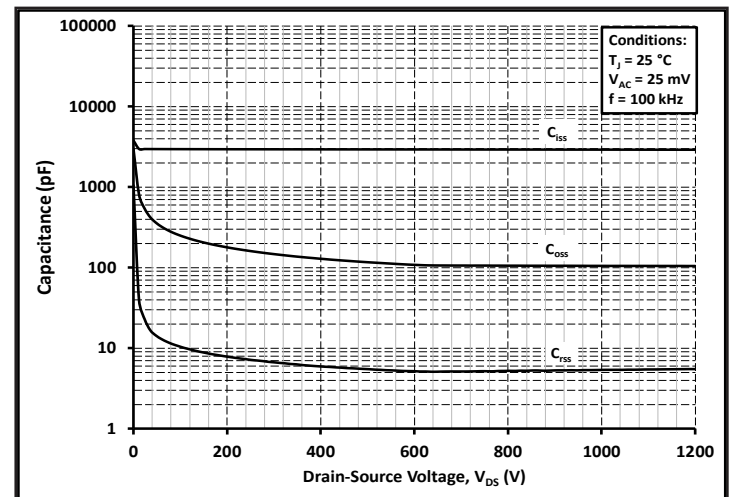


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 1200V)

Typical Performance

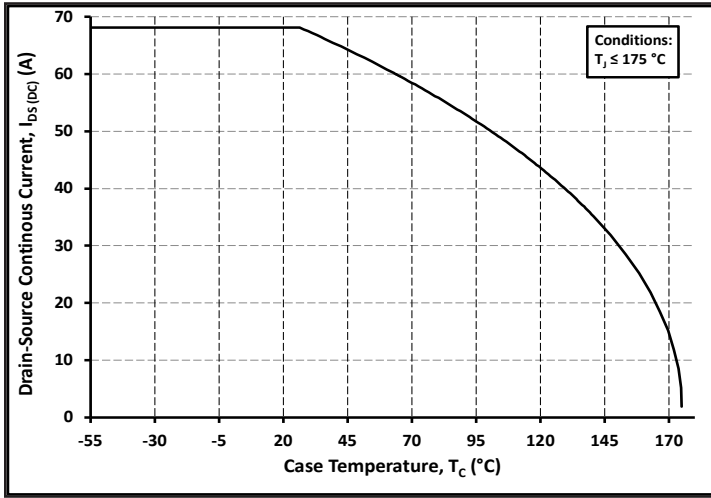


Figure 19. Continuous Drain Current Derating vs. Case Temperature

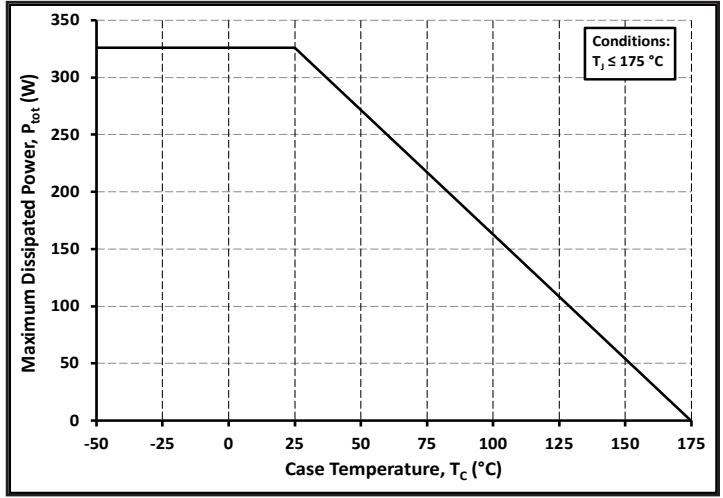


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature

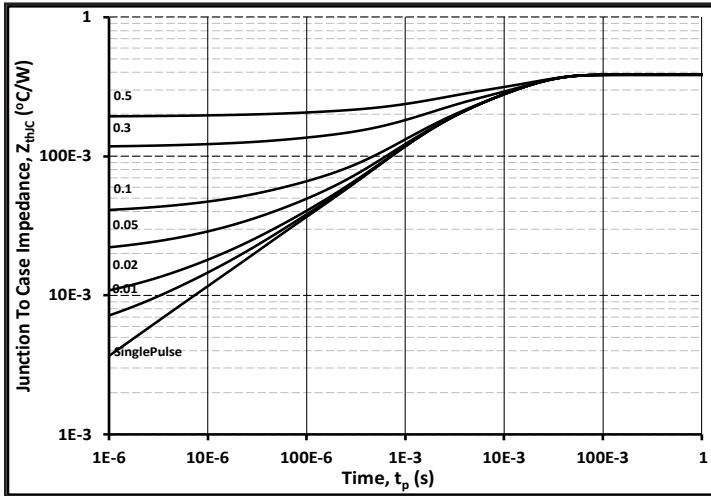


Figure 21. Transient Thermal Impedance (Junction - Case)

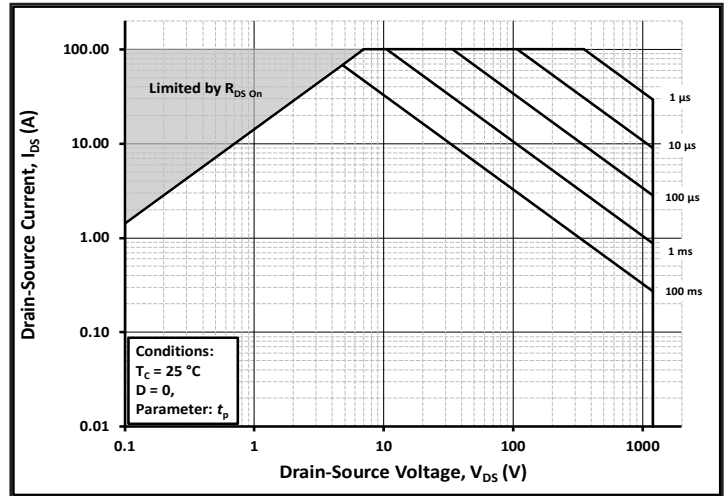


Figure 22. Safe Operating Area

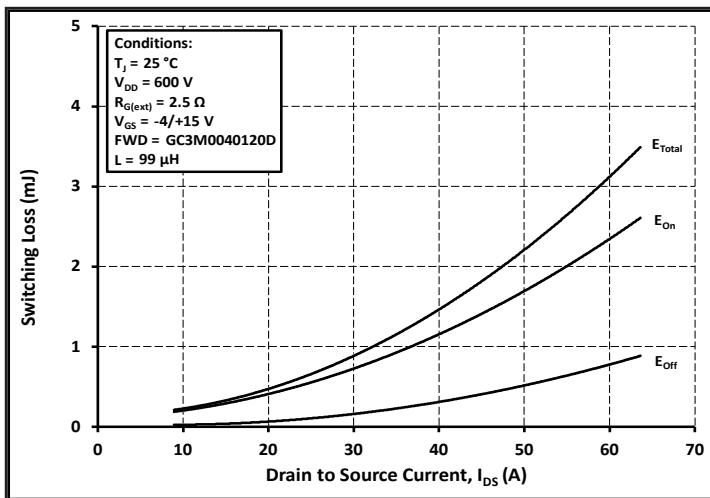


Figure 23. Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD} = 600V$ )

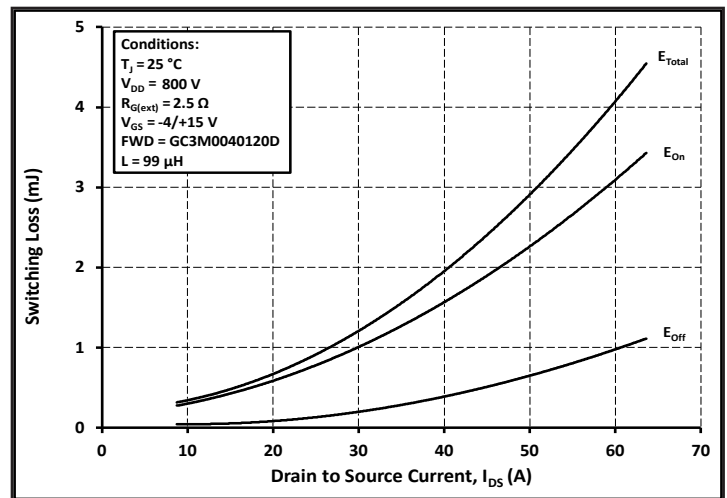


Figure 24. Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD} = 800V$ )

Typical Performance

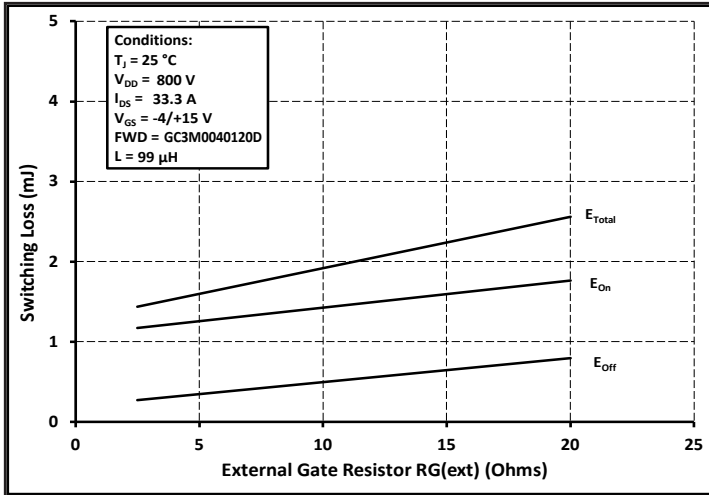


Figure 25. Clamped Inductive Switching Energy vs.  $R_{G(ext)}$

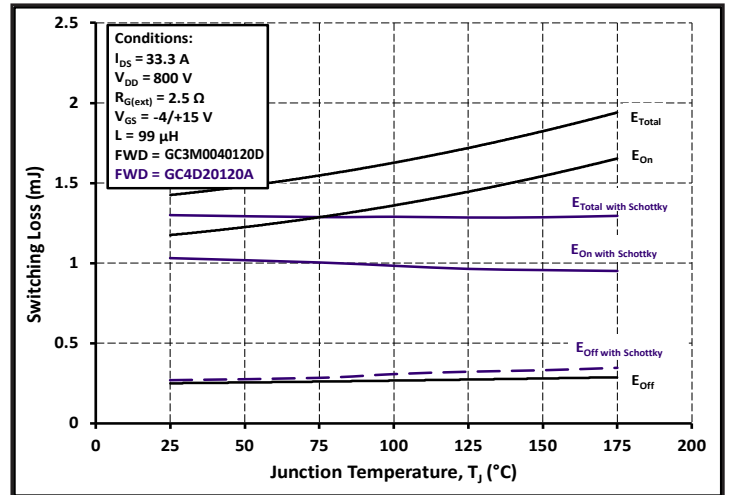


Figure 26. Clamped Inductive Switching Energy vs. Temperature

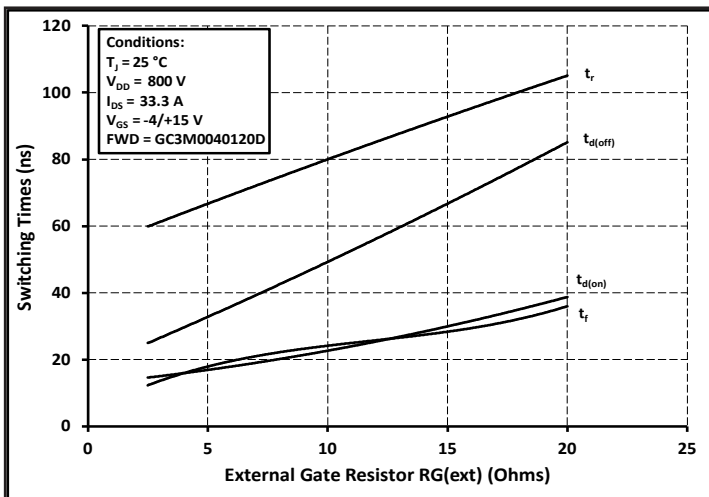


Figure 27. Switching Times vs.  $R_{G(ext)}$

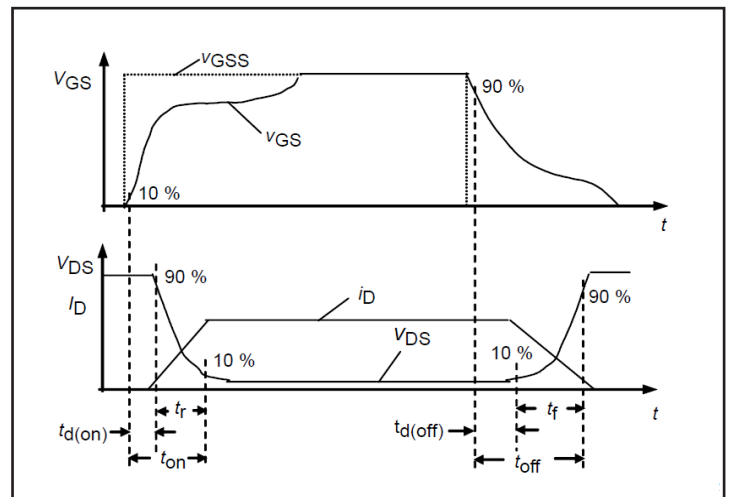


Figure 28. Switching Times Definition



**Test Circuit Schematic**

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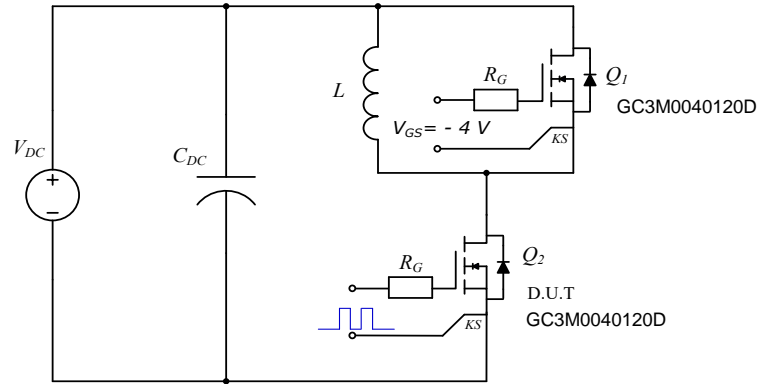
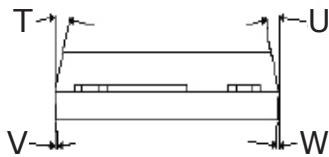
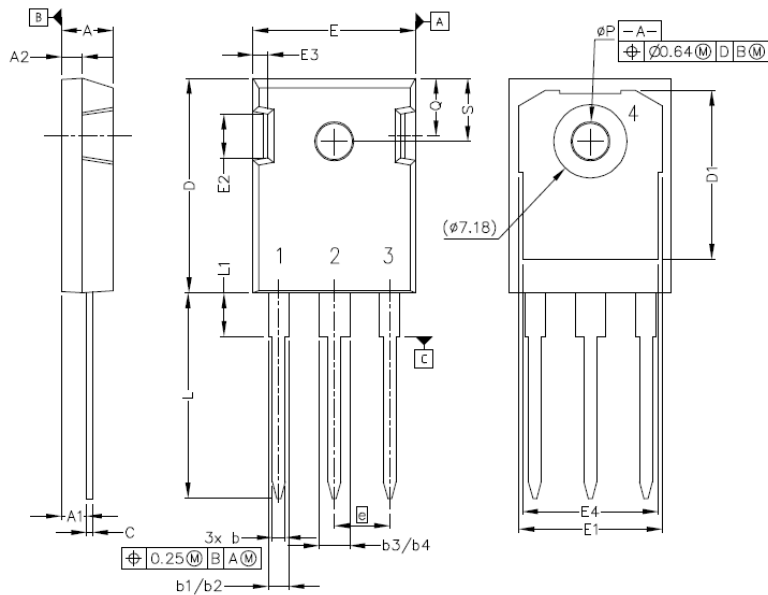


Figure 29. Clamped Inductive Switching  
Waveform Test Circuit

Note (3): Turn-off and Turn-on switching energy and timing values measured using SiC MOSFET Body Diode as shown above.

## Package Dimensions

Package TO-247-3

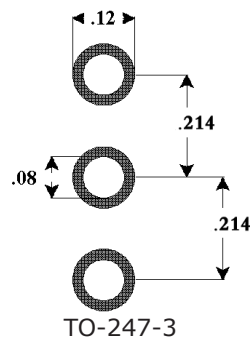


Pinout Information:

- Pin 1 = Gate
- Pin 2, 4 = Drain
- Pin 3 = Source

| POS | Inches   |      | Millimeters |       |
|-----|----------|------|-------------|-------|
|     | Min      | Max  | Min         | Max   |
| A   | .190     | .205 | 4.83        | 5.21  |
| A1  | .090     | .100 | 2.29        | 2.54  |
| A2  | .075     | .085 | 1.91        | 2.16  |
| b   | .042     | .052 | 1.07        | 1.33  |
| b1  | .075     | .095 | 1.91        | 2.41  |
| b2  | .075     | .085 | 1.91        | 2.16  |
| b3  | .113     | .133 | 2.87        | 3.38  |
| b4  | .113     | .123 | 2.87        | 3.13  |
| c   | .022     | .027 | 0.55        | 0.68  |
| D   | .819     | .831 | 20.80       | 21.10 |
| D1  | .640     | .695 | 16.25       | 17.65 |
| D2  | .037     | .049 | 0.95        | 1.25  |
| E   | .620     | .635 | 15.75       | 16.13 |
| E1  | .516     | .557 | 13.10       | 14.15 |
| E2  | .145     | .201 | 3.68        | 5.10  |
| E3  | .039     | .075 | 1.00        | 1.90  |
| E4  | .487     | .529 | 12.38       | 13.43 |
| e   | .214 BSC |      | 5.44 BSC    |       |
| N   | 3        |      | 3           |       |
| L   | .780     | .800 | 19.81       | 20.32 |
| L1  | .161     | .173 | 4.10        | 4.40  |
| ØP  | .138     | .144 | 3.51        | 3.65  |
| Q   | .216     | .236 | 5.49        | 6.00  |
| S   | .238     | .248 | 6.04        | 6.30  |
| T   | 9°       | 11°  | 9°          | 11°   |
| U   | 9°       | 11°  | 9°          | 11°   |
| V   | 2°       | 8°   | 2°          | 8°    |
| W   | 2°       | 8°   | 2°          | 8°    |

## Recommended Solder Pad Layout



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